Notice for TAIYO YUDEN products

Please read this notice before using the TAIYO YUDEN products.

/!\ REMINDERS

Product Information in this Catalog

Product information in this catalog is as of January 2021. All of the contents specified herein and production status of the products listed in this catalog are subject to change without notice due to technical improvement of our products, etc. Therefore, please check for the latest information carefully before practical application or use of our products.

Please note that TAIYO YUDEN shall not be in any way responsible for any damages and defects in products or equipment incorporating our products, which are caused under the conditions other than those specified in this catalog or individual product specification sheets.

Approval of Product Specifications

Please contact TAIYO YUDEN for further details of product specifications as the individual product specification sheets are available. When using our products, please be sure to approve our product specifications or make a written agreement on the product specification with TAIYO YUDEN in advance.

Pre-Evaluation in the Actual Equipment and Conditions

Please conduct validation and verification of our products in actual conditions of mounting and operating environment before using our products.

Limited Application

1. Equipment Intended for Use

The products listed in this catalog are intended for general-purpose and standard use in general electronic equipment (e.g., AV equipment, OA equipment, home electric appliances, office equipment, information and communication equipment including, without limitation, mobile phone, and PC) and other equipment specified in this catalog or the individual product specification sheets.

TAIYO YUDEN has the line-up of the products intended for use in automotive electronic equipment, telecommunications infrastructure and industrial equipment, or medical devices classified as GHTF Classes A to C (Japan Classes I to III). Therefore, when using our products for these equipment, please check available applications specified in this catalog or the individual product specification sheets and use the corresponding products.

2. Equipment Requiring Inquiry

Please be sure to contact TAIYO YUDEN for further information before using the products listed in this catalog for the following equipment (excluding intended equipment as specified in this catalog or the individual product specification sheets) which may cause loss of human life, bodily injury, serious property damage and/or serious public impact due to a failure or defect of the products and/or malfunction attributed thereto.

- (1) Transportation equipment (automotive powertrain control system, train control system, and ship control system, etc.)
- (2) Traffic signal equipment
- (3) Disaster prevention equipment, crime prevention equipment
- (4) Medical devices classified as GHTF Class C (Japan Class III)
- (5) Highly public information network equipment, dataprocessing equipment (telephone exchange, and base station, etc.)
- (6) Any other equipment requiring high levels of quality and/or reliability equal to the equipment listed above

3. Equipment Prohibited for Use

Please do not incorporate our products into the following equipment requiring extremely high levels of safety and/or reliability.

- (1) Aerospace equipment (artificial satellite, rocket, etc.)
- (2) Aviation equipment *1
- (3) Medical devices classified as GHTF Class D (Japan Class IV), implantable medical devices *2

- (4) Power generation control equipment (nuclear power, hydroelectric power, thermal power plant control system, etc.)
- (5) Undersea equipment (submarine repeating equipment, underwater work equipment, etc.)
- (6) Military equipment
- (7) Any other equipment requiring extremely high levels of safety and/or reliability equal to the equipment listed above

*Notes:

- 1. There is a possibility that our products can be used only for aviation equipment that does not directly affect the safe operation of aircraft (e.g., in-flight entertainment, cabin light, electric seat, cooking equipment) if such use meets requirements specified separately by TAIYO YUDEN. Please be sure to contact TAIYO YUDEN for further information before using our products for such aviation equipment.
- Implantable medical devices contain not only internal unit which is implanted in a body, but also external unit which is connected to the internal unit.

4. Limitation of Liability

Please note that unless you obtain prior written consent of TAIYO YUDEN, TAIYO YUDEN shall not be in any way responsible for any damages incurred by you or third parties arising from use of the products listed in this catalog for any equipment that is not intended for use by TAIYO YUDEN, or any equipment requiring inquiry to TAIYO YUDEN or prohibited for use by TAIYO YUDEN as described above.

Safety Design

When using our products for high safety and/or reliability-required equipment or circuits, please fully perform safety and/or reliability evaluation. In addition, please install (i) systems equipped with a protection circuit and a protection device and/or (ii) systems equipped with a redundant circuit or other system to prevent an unsafe status in the event of a single fault for a failsafe design to ensure safety.

Intellectual Property Rights

Information contained in this catalog is intended to convey examples of typical performances and/or applications of our products and is not intended to make any warranty with respect to the intellectual property rights or any other related rights of TAIYO YUDEN or any third parties nor grant any license under such rights.

Limited Warranty

Please note that the scope of warranty for our products is limited to the delivered our products themselves and TAIYO YUDEN shall not be in any way responsible for any damages resulting from a failure or defect in our products. Notwithstanding the foregoing, if there is a written agreement (e.g., supply and purchase agreement, quality assurance agreement) signed by TAIYO YUDEN and your company, TAIYO YUDEN will warrant our products in accordance with such agreement

■ TAIYO YUDEN's Official Sales Channel

The contents of this catalog are applicable to our products which are purchased from our sales offices or authorized distributors (hereinafter "TAIYO YUDEN's official sales channel"). Please note that the contents of this catalog are not applicable to our products purchased from any seller other than TAIYO YUDEN's official sales channel.

Caution for Export

2021

Some of our products listed in this catalog may require specific procedures for export according to "U.S. Export Administration Regulations", "Foreign Exchange and Foreign Trade Control Law" of Japan, and other applicable regulations. Should you have any questions on this matter, please contact our sales staff.

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WIRE-WOUND CHIP INDUCTORS FOR SIGNAL LINES (LB SERIES M TYPE)

■PARTS NUMBER

* Operating Temp.: -40~+105°C (Including self-generated heat)



①Series name

Code	Series name
LBM△	Wound chip inductor for signal line

②Dimensions (L×W)

<u> </u>		
Code	Type (inch)	Dimensions (L×W) [mm]
2016	2016(0806)	2.0 × 1.6

③Packaging		
	Code	Packaging

4 Nominal inductance

Code (example)	Nominal inductance[μ H]
R12	0.12
1R0	1.0
100	10
101	100

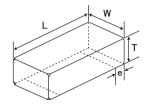
※R=Decimal point

⑤Inductance tolerance

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	Code	Inductance tolerance
	J	±5%

6 Internal code

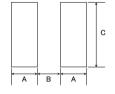
■ STANDARD EXTERNAL DIMENSIONS / STANDARD QUANTITY



Recommended Land Patterns

- •Mounting and soldering conditions should be checked beforehand.
- *Applicable soldering process to these products is reflow soldering only.

Type	Α	В	С
LBM 2016	0.6	1.0	1.8
			Unit:mm



	Tumo			1 W		W T e		Standard quantity [pcs]	
	Туре	L	VV	'	е	Paper tape	Embossed tape		
L	BM 2016	2.0±0.2 (0.08±0.008)	1.6±0.2 (0.063±0.008)	1.6±0.2 (0.063±0.008)	0.5±0.2 (0.02±0.008)	-	2000		

Unit:mm(inch)

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for General Electronic Equipment

				_	Self-resonant	505.11		Measuring
Parts number	EHS	Nominal inductance [μ H]	Inductance tolerance	Q (min.)	frequency [MHz] (min.)	DC Resistance [Ω](±30%)	Rated current [mA] (max.)	frequency [MHz]
LBM 2016TR12J	RoHS	0.12	±5%	30	600	0.13	610	25.2
LBM 2016TR15J	RoHS	0.15	±5%	30	550	0.15	570	25.2
LBM 2016TR18J	RoHS	0.18	±5%	30	500	0.15	560	25.2
LBM 2016TR22J	RoHS	0.22	±5%	30	450	0.20	520	25.2
LBM 2016TR27J	RoHS	0.27	±5%	30	425	0.21	510	25.2
LBM 2016TR33J	RoHS	0.33	±5%	30	400	0.21	490	25.2
LBM 2016TR39J	RoHS	0.39	±5%	30	375	0.26	440	25.2
LBM 2016TR47J	RoHS	0.47	±5%	30	350	0.26	430	25.2
LBM 2016TR56J	RoHS	0.56	±5%	30	300	0.29	410	25.2
LBM 2016TR68J	RoHS	0.68	±5%	30	270	0.32	400	25.2
LBM 2016TR82J	RoHS	0.82	±5%	30	250	0.34	390	25.2
LBM 2016T1R0J	RoHS	1.0	±5%	30	220	0.38	385	7.96
LBM 2016T1R2J	RoHS	1.2	±5%	30	180	0.41	370	7.96
LBM 2016T1R5J	RoHS	1.5	±5%	30	135	0.47	350	7.96
LBM 2016T1R8J	RoHS	1.8	±5%	30	100	0.48	345	7.96
LBM 2016T2R2J	RoHS	2.2	±5%	30	75	0.54	340	7.96
LBM 2016T2R7J	RoHS	2.7	±5%	30	55	0.59	310	7.96
LBM 2016T3R3J	RoHS	3.3	±5%	30	48	0.68	290	7.96
LBM 2016T3R9J	RoHS	3.9	±5%	30	43	0.74	275	7.96
LBM 2016T4R7J	RoHS	4.7	±5%	30	40	0.78	270	7.96
LBM 2016T5R6J	RoHS	5.6	±5%	25	36	0.88	255	7.96
LBM 2016T6R8J	RoHS	6.8	±5%	25	33	0.97	240	7.96
LBM 2016T8R2J	RoHS	8.2	±5%	25	30	1.1	225	7.96
LBM 2016T100J	RoHS	10	±5%	25	27	1.2	215	2.52
LBM 2016T120J	RoHS	12	±5%	25	23	1.4	200	2.52
LBM 2016T150J	RoHS	15	±5%	25	20	1.5	190	2.52
LBM 2016T180J	RoHS	18	±5%	25	18	2.5	150	2.52
LBM 2016T220J	RoHS	22	±5%	25	17	2.8	140	2.52
LBM 2016T270J	RoHS	27	±5%	25	16	3.2	130	2.52
LBM 2016T330J	RoHS	33	±5%	25	15	3.6	125	2.52
LBM 2016T390J	RoHS	39	±5%	20	14	3.9	120	2.52
LBM 2016T470J	RoHS	47	±5%	20	13	4.1	115	2.52
LBM 2016T560J	RoHS	56	±5%	20	12	5.9	95	2.52
LBM 2016T680J	R₀HS	68	±5%	20	11	7.0	90	2.52
LBM 2016T820J	R₀HS	82	±5%	20	10	7.7	85	2.52
LBM 2016T101J	RoHS	100	±5%	15	9.0	8.0	80	0.796
LBM 2016T151J	RoHS	150	±5%	15	6.5	13.5	69	0.796
LBM 2016T181J	R₀HS	180	±5%	15	6.0	15	67	0.796
LBM 2016T221J	RoHS	220	±5%	15	5.5	18	65	0.796

XX) Rated Current : The maximum DC value having inductance decrease within 10 % and temperature increase within 20 degC by the application of DC bias.

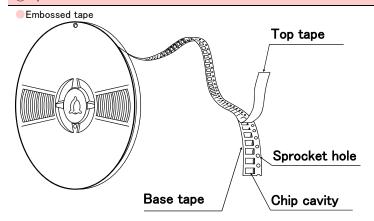
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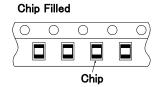
WIRE-WOUND CHIP INDUCTORS (LB SERIES), WIRE-WOUND CHIP POWER INDUCTORS (CB SERIES), WIRE-WOUND CHIP INDUCTORS FOR SIGNAL LINES (LB SERIES M TYPE)

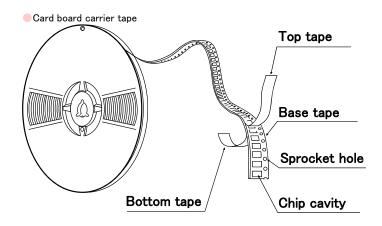
PACKAGING

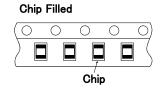
1 Minimum Quantity Standard Quantity [pcs] Туре Paper Tape Embossed Tape LB C3225 1000 CB C3225 LB 3218 2000 LB R2518 LB C2518 2000 LB 2518 CB 2518 CB C2518 LBM2016 LB C2016 LB 2016 2000 CB 2016 CB C2016 LB 2012 LB C2012 LB R2012 3000 CB 2012 CB C2012 CB L2012 4000 LB 1608 4000 LBMF1608 3000 CBMF1608

②Tape material



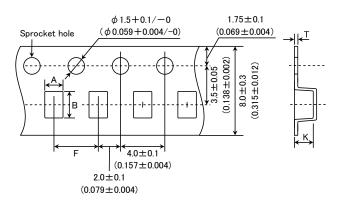






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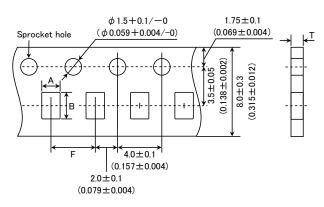
Embossed Tape (0.315 inches wide)



Т	Chip	cavity	Insertion pitch	Tape thickness	
Туре	Α	В	F	Т	K
LBM2016	1.75±0.1	2.1±0.1	4.0±0.1	0.3±0.05	1.9max.
	(0.069±0.004)	(0.083±0.004)	(0.157±0.004)	(0.012±0.002)	(0.075max.)
LB C3225	2.8±0.1	3.5±0.1	4.0±0.1	0.3±0.05	4.0max.
CB C3225	(0.110±0.004)	(0.138±0.004)	(0.157±0.004)	(0.012±0.002)	(0.157max.)
LB 3218	2.1±0.1	3.5±0.1	4.0±0.1	0.3±0.05	2.2max.
	(0.083±0.004)	(0.138±0.004)	(0.157±0.004)	(0.012±0.002)	(0.087max.)
LB 2518 CB 2518 LB C2518 CB C2518 LB R2518	2.15±0.1	2.7±0.1	4.0±0.1	0.3±0.05	2.2max.
	(0.085±0.004)	(0.106±0.004)	(0.157±0.004)	(0.012±0.002)	(0.087max.)
LB 2016 CB 2016 LB C2016 CB C2016	1.75±0.1 (0.069±0.004)	2.1±0.1 (0.083±0.004)	4.0±0.1 (0.157±0.004)	0.3±0.05 (0.012±0.002)	1.9max. (0.075max.)
LB 2012 CB 2012 LB C2012 CB C2012 LB R2012	1.45±0.1 (0.057±0.004)	2.25±0.1 (0.089±0.004)	4.0±0.1 (0.157±0.004)	0.25±0.05 (0.010±0.002)	1.45max. (0.057max.)
LBMF1608	1.1±0.1	1.9±0.1	4.0±0.1	0.25±0.05	1.2max.
CBMF1608	(0.043±0.004)	(0.075±0.004)	(0.157±0.004)	(0.010±0.002)	(0.047max.)

Unit:mm(inch)

Card board carrier tape (0.315 inches wide)

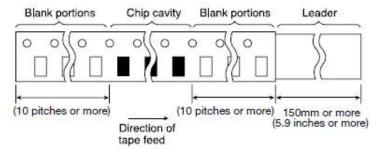


Turna	Chip	cavity	Insertion pitch	Tape thickness
Туре	Α	В	F	T
CB L2012	1.55±0.1	2.3±0.1	4.0±0.1	1.1max.
OB L2012	(0.061 ± 0.004)	(0.091 ± 0.004)	(0.157 ± 0.004)	(0.043max.)
LB 1608	1.0±0.1	1.8±0.1	4.0±0.1	1.1max.
LB 1006	(0.039 ± 0.004)	(0.071 ± 0.004)	(0.157 ± 0.004)	(0.043max.)

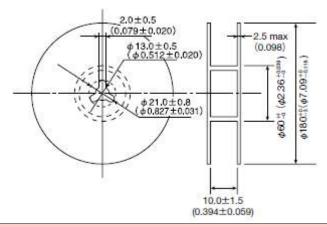
Unit:mm(inch)

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4 Leader and Blank Portion



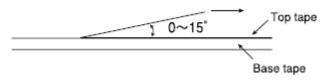
⑤Reel Size



©Top Tape Strength

The top tape requires a peel-off force 0.2 to 0.7N in the direction of the arrow as illustrated below.

Pull direction



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WIRE-WOUND CHIP INDUCTORS (LB SERIES), WIRE-WOUND CHIP POWER INDUCTORS (CB SERIES), WIRE-WOUND CHIP INDUCTORS FOR SIGNAL LINES (LB SERIES M TYPE)

RELIABILITY DATA

1.Operating temper	ature Range					
	LB, LBC, LBR, LBMF Series					
Specified Value	CB, CBC, CBL, CBMF Series					
	LBM Series					
		1				
2. Storage Tempera	ture Range (after soldering)					
	LB, LBC, LBR, LBMF Series					
Specified Value	CB, CBC, CBL, CBMF Series	-40~+85°C				
	LBM Series	7				
Test Methods and Remarks	LB, CB Series: Please refer the term of "7. storage conditions" in precaution	ns.				
3.Rated Current						
	LB, LBC, LBR, LBMF Series					
Specified Value	CB, CBC, CBL, CBMF Series	Within the specified tolerance				
	LBM Series					
4.Inductance						
	LB, LBC, LBR, LBMF Series					
Specified Value	CB, CBC, CBL, CBMF Series	Within the specified tolerance				
	LBM Series					
Test Methods and Remarks	LB·LBC·LBR·CB·CBC·CBL·LBMF·CBMF·LBM Series Measuring equipment :LCR Mater(HP4285A or its of the Measuring frequency : Specified frequency	equivalent)				
5.Q						
	LB, LBC, LBR, LBMF Series					
Specified Value	CB, CBC, CBL, CBMF Series					
	LBM Series	Within the specified tolerance				
Test Methods and Remarks	LBM Series Measuring equipment : LCR Mater(HP4285A or its ed) Measuring frequency : Specified frequency	quivalent)				
6.DC Resisitance						
	LB, LBC, LBR, LBMF Series					
Specified Value	CB, CBC, CBL, CBMF Series	Within the specified tolerance				
	LBM Series					
Test Methods and Remarks	Measuring equipment : DC Ohmmeter (HIOKI 3227 or its equivalent)					
7.Self-Resonant Fr	equency					
	LB, LBC, LBR, LBMF Series					
Specified Value	CB, CBC, CBL, CBMF Series	Within the specified tolerance				
	LBM Series					
Test Methods and Remarks	Measuring equipment : Impedance analyzer (HP4291A or its equivalent)					

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8.Temperature Cha	racteristic				
	LBM2016				Inductance change : Within±5%
	LB1608	LB2012	LBR2012	CB2012	
	CBL2012	LB2016	CB2016	LB2518	Inductance change : Within±20%
Specified Value	LBR2518	CB2518	LBC3225	CBC3225	
	LBMF1608	CBMF1608	LBC2016	CBC2016	Maria 1 0507
	LBC2518	CBC2518	LB3218		Inductance change : Within±25%
	LBC2012	CBC2012			Inductance change : Within±35%
Test Methods and Remarks	Based on the inductance at 20°C and Measured at the ambient of −40°C∼+85°C.				

9.Rasistance to Flex	xure of Substrate			
Specified Value	LB, LBC, LBR, LBMF Series	No damage.		
	CB, CBC, CBL, CBMF Series			
	LBM Series			
	Warp : 2mm(LB+LBC+LBR+CB+CBC+CBL+LBM+LBMF+CBMF Series)			
Test Methods and Remarks	Test substrate : Glass epoxy-resin substrate Thickness : 0.8mm(LB1608·LBMF1608·CBMF1608) : 1.0mm(Others) Pressing jig 10 20 R340 Board A5±2mm A5±2mm A5±2mm			

10.Body Strength		
Specified Value	LB, LBC, LBR, LBMF Series	No damage.
	CB, CBC, CBL, CBMF Series	
	LBM Series	
Test Methods and Remarks	LB·LBC·LBR·CB·CBC·CBL·LBM Applied force : 10N Duration : 10sec. LB1608·LBMF1608·CBMF1608 Applied force : 5N Duration : 10sec.	

11.Adhesion of term	ninal electrode		
	LB, LBC, LBR, LBMF Series		No abnormality.
Specified Value	CB, CBC, CBL, CBMF Series		
	LBM Series		
Test Methods and Remarks	Applied force Duration Test substrate LB1608 · CBMF1608	CBC•CBL•LBM•LBMF•CBMF : 10N to X and Y directions : 5 sec. : Printed board 3•LBMF1608 : 5N to X and Y directions : 5 sec. : Printed board	

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12.Resistance to vi	pration					
			T T			
	LB, LBC, LBR, LBMF Series		Inductance change: Within±10%			
Specified Value	CB, CBC, CBL, CBMF Series		No significant abnormality in appearance.			
	LBM Series		Inductance change : Within±5% No significant abnormality in appearance.			
	LB·LBR·LBC·CB·CBC·CBL·LBM·LBMF·CBMF:					
	The given sample is soldered to the board and then it is tested depending on the conditions of the following table.					
Test Methods and Remarks	Vibration Frequency	10~55Hz	1. 100 (0)			
	Total Amplitude Sweeping Method	1.5mm (May not exceed acceled to 10Hz to 55Hz to 10Hz for 1min				
	Owceping Method	X	11.			
	Time	Y For 2 hours or	n each X, Y, and Z axis.			
	Z					
	Recovery : At least 2 hrs of recovery under the standard condition after the test, followed by the measurement within 48 hrs.					
13.Drop test						
	LB, LBC, LBR, LBMF Series					
Specified Value	CB, CBC, CBL, CBMF Series		_			
•	LBM Series					
	<u>-</u>		1			
14.Solderability						
17.00iderability	ID IDO IDD IDMC Co					
0 15 114 1	LB, LBC, LBR, LBMF Series		4.1			
Specified Value	CB, CBC, CBL, CBMF Series		At least 90% of surface of terminal electrode is covered by new			
	LBM Series					
	LB·LBC·LBR·CB·CBC·CBL					
Test Methods and Remarks	'	5±5°C :0.5sec				
Remarks		thanol solution with 25% of col-	ophony			
	TIGA . IIIO	THAT OF COLUMN THE POPULATION OF COLUMN THE PO	opriority			
15.Resistance to so	Iderina					
TO. Nesistance to se	LB. LBC. LBR. LBMF Series					
0 :5 17/1			Inductance change : Within±10%			
Specified Value	CB, CBC, CBL, CBMF Series					
	LBM Series		Inductance change : Within±5%			
Test Methods and	LB·LBC·LBR·CB·CBC·CBL		manusture at 260 °C for 5000			
	3 times of reflow oven at 230°C MIN for 40sec. with peak temperature at 260 °C for 5sec. Recovery : At least 2 hrs of recovery under the standard condition after the test, followed by the measurement within 48 hrs.					
nemarks	Recovery : At least 2 hrs of	recovery under the standard of				
nemarks	Recovery : At least 2 hrs of	f recovery under the standard co				
	·	f recovery under the standard co				
	olvent	f recovery under the standard co				
16.Resisitance to s	blvent LB, LBC, LBR, LBMF Series	f recovery under the standard c				
16.Resisitance to s	Divent LB, LBC, LBR, LBMF Series CB, CBC, CBL, CBMF Series	f recovery under the standard c				
16.Resisitance to se	blvent LB, LBC, LBR, LBMF Series	f recovery under the standard o				
16.Resisitance to se Specified Value	LB, LBC, LBR, LBMF Series CB, CBC, CBL, CBMF Series LBM Series Solvent temperature : Roo	om temperature				
16.Resisitance to see Specified Value Test Methods and	LB, LBC, LBR, LBMF Series CB, CBC, CBL, CBMF Series LBM Series Solvent temperature : Roc Type of solvent : Iso	om temperature propyl alcohol				
16.Resisitance to see Specified Value Test Methods and	LB, LBC, LBR, LBMF Series CB, CBC, CBL, CBMF Series LBM Series Solvent temperature : Roc Type of solvent : Iso	om temperature				
16.Resisitance to see Specified Value Test Methods and Remarks	LB, LBC, LBR, LBMF Series CB, CBC, CBL, CBMF Series LBM Series Solvent temperature : Roc Type of solvent : Iso	om temperature propyl alcohol				
16.Resisitance to see Specified Value Test Methods and	LB, LBC, LBR, LBMF Series CB, CBC, CBL, CBMF Series LBM Series Solvent temperature : Roo Type of solvent : Iso Cleaning conditions : 90s	om temperature propyl alcohol				
16.Resisitance to see Specified Value Test Methods and Remarks	LB, LBC, LBR, LBMF Series CB, CBC, CBL, CBMF Series LBM Series Solvent temperature : Roo Type of solvent : Iso Cleaning conditions : 90s	om temperature propyl alcohol	ondition after the test, followed by the measurement within 48 hrs.			
16.Resisitance to see Specified Value Test Methods and Remarks	LB, LBC, LBR, LBMF Series CB, CBC, CBL, CBMF Series LBM Series Solvent temperature : Roo Type of solvent : Iso Cleaning conditions : 90s	om temperature propyl alcohol				
16.Resisitance to see Specified Value Test Methods and Remarks	LB, LBC, LBR, LBMF Series CB, CBC, CBL, CBMF Series LBM Series Solvent temperature : Roo Type of solvent : Iso Cleaning conditions : 90s	om temperature propyl alcohol	Inductance change: Within±10%			
16.Resisitance to see Specified Value Test Methods and Remarks 17.Thermal shock Specified Value Test Methods and	LB, LBC, LBR, LBMF Series CB, CBC, CBL, CBMF Series LBM Series Solvent temperature : Root Type of solvent : Isol Cleaning conditions : 90s LB, LBC, LBR, LBMF Series CB, CBC, CBL, CBMF Series	om temperature propyl alcohol s. Immersion and cleaning.	Inductance change: Within±10%			
16.Resisitance to see Specified Value Test Methods and Remarks 17.Thermal shock Specified Value Test Methods and	LB, LBC, LBR, LBMF Series CB, CBC, CBL, CBMF Series LBM Series Solvent temperature : Roo Type of solvent : Isop Cleaning conditions : 90s LB, LBC, LBR, LBMF Series CB, CBC, CBL, CBMF Series LBM Series LB*LBC*LBR*CB*CBC*CBL The given sample is soldered to	om temperature propyl alcohol s. Immersion and cleaning. •LBM•LBMF•CBMF: to the board and then its Induct	Inductance change: Within±10%			
Specified Value Test Methods and Remarks	LB, LBC, LBR, LBMF Series CB, CBC, CBL, CBMF Series LBM Series Solvent temperature : Roo Type of solvent : Iso Cleaning conditions : 90s LB, LBC, LBR, LBMF Series CB, CBC, CBL, CBMF Series LBM Series LB*LBC*LBR*CB*CBC*CBL The given sample is soldered in Conditions.	om temperature propyl alcohol s. Immersion and cleaning. • LBM • LBMF • CBMF: to the board and then its Inductions of 1 cycle	Inductance change: Within±10% No significant abnormality in appearance.			
16.Resisitance to see Specified Value Test Methods and Remarks 17.Thermal shock Specified Value Test Methods and	LB, LBC, LBR, LBMF Series CB, CBC, CBL, CBMF Series LBM Series Solvent temperature : Roo Type of solvent : Isol Cleaning conditions : 90s LB, LBC, LBR, LBMF Series CB, CBC, CBL, CBMF Series LB*LBC*LBR*CB*CBC*CBL The given sample is soldered is Condit Step Temperature (%)	om temperature propyl alcohol s. Immersion and cleaning. •LBM•LBMF•CBMF: to the board and then its Inductions of 1 cycle C) Duration (min)	Inductance change: Within±10% No significant abnormality in appearance.			
16.Resisitance to see Specified Value Test Methods and Remarks 17.Thermal shock Specified Value Test Methods and	LB, LBC, LBR, LBMF Series CB, CBC, CBL, CBMF Series LBM Series Solvent temperature : Roc Type of solvent : Isol Cleaning conditions : 90s LB, LBC, LBR, LBMF Series CB, CBC, CBL, CBMF Series LBM Series LB*LBC*LBR*CB*CBC*CBL The given sample is soldered in Condit Step Temperature (% 1 -40±3)	om temperature propyl alcohol s. Immersion and cleaning. *LBM*LBMF*CBMF: to the board and then its Inductations of 1 cycle C) Duration (min) 30±3	Inductance change: Within±10% No significant abnormality in appearance.			
16.Resisitance to see Specified Value Test Methods and Remarks 17.Thermal shock Specified Value Test Methods and	LB, LBC, LBR, LBMF Series CB, CBC, CBL, CBMF Series LBM Series Solvent temperature : Roo Type of solvent : Isol Cleaning conditions : 90s LB, LBC, LBR, LBMF Series CB, CBC, CBL, CBMF Series LB*LBC*LBR*CB*CBC*CBL The given sample is soldered is Condit Step Temperature (%)	om temperature propyl alcohol s. Immersion and cleaning. *LBM*LBMF*CBMF: to the board and then its Inductations of 1 cycle C) Duration (min) 30±3	Inductance change: Within±10% No significant abnormality in appearance.			
16.Resisitance to see Specified Value Test Methods and Remarks 17.Thermal shock Specified Value Test Methods and	LB, LBC, LBR, LBMF Series CB, CBC, CBL, CBMF Series LBM Series Solvent temperature : Roc Type of solvent : Isop Cleaning conditions : 90s LB, LBC, LBR, LBMF Series CB, CBC, CBL, CBMF Series LBM Series LB*LBC*LBR*CB*CBC*CBL The given sample is soldered in Condit Step Temperature (% 1 -40±3) 2 Room temperature	om temperature propyl alcohol s. Immersion and cleaning. *LBM*LBMF*CBMF: to the board and then its Inductations of 1 cycle (C) Duration (min) 30±3 ure Within 3 30±3	Inductance change: Within±10% No significant abnormality in appearance.			

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18.Damp heat life to	est				
	LB, LBC, LBR, LBN	MF Series			
Specified Value	CB, CBC, CBL, CBMF Series		Inductance change : Within±10%		
	LBM Series No significant abnormality in appearance.				
	Temperature	: 60±2°C			
Test Methods and Remarks	Humidity	: 90~95%RH			
	Duration	: 1000 hrs			
	Recovery	: At least 2 hrs of recovery under the	ne standard condition after the test, followed by the measurement within 48 hrs.		
19.Loading under da		15.0			
	LB, LBC, LBR, LBN		Inductance change : Within±10%		
	CB, CBC, CBL, CBMF Series		No significant abnormality in appearance.		
Specified Value	LBM Series				
Test Methods and	Temperature	: 60±2°C			
Remarks	Humidity : 90∼95%RH Duration : 1000 hrs				
	Applied current	: Rated current			
	Recovery	: At least 2 hrs of recovery under the	ne standard condition after the test, followed by the measurement within 48 hrs.		
20.High temperature	e life test				
	LB, LBC, LBR, LBN	MF Series	_		
Specified Value	CB, CBC, CBL, CB	MF Series	Inductance change : Within±10%		
	LBM Series		No significant abnormality in appearance.		
Test Methods and	Temperature	: 85±2°C	·		
Remarks	Duration	: 1000 hrs			
	Recovery	: At least 2 hrs of recovery under the	ne standard condition after the test, followed by the measurement within 48 hrs.		
21.Loading at high t	temperature life test				
	LB, LBC, LBR, LBMF Series		Inductance change: Within±10% (LBC3225 Series: Within±20%)		
C:E V-	LB, LBC, LBR, LBR	nr Series	No significant abnormality in appearance.		
Specified Value	CB, CBC, CBL, CB	MF Series	<u> </u>		
	LBM Series				
		: 85±2°C			
Test Methods and	LBM Series Temperature Duration	: 85±2°C : 1000 hrs			
Test Methods and Remarks	Temperature Duration Applied current	: 1000 hrs : Rated current			
	Temperature Duration	: 1000 hrs : Rated current	ne standard condition after the test, followed by the measurement within 48 hrs.		
Remarks	Temperature Duration Applied current Recovery	: 1000 hrs : Rated current			
	Temperature Duration Applied current Recovery	: 1000 hrs : Rated current : At least 2 hrs of recovery under th			
Remarks	Temperature Duration Applied current Recovery	: 1000 hrs : Rated current : At least 2 hrs of recovery under th	ne standard condition after the test, followed by the measurement within 48 hrs.		
Remarks	Temperature Duration Applied current Recovery	: 1000 hrs : Rated current : At least 2 hrs of recovery under the			
Remarks 22.Low temperature	Temperature Duration Applied current Recovery elife test LB, LBC, LBR, LBN	: 1000 hrs : Rated current : At least 2 hrs of recovery under the	Inductance change: Within±10%		
22.Low temperature Specified Value	Temperature Duration Applied current Recovery e life test LB, LBC, LBR, LBM CB, CBC, CBL, CB LBM Series Temperature	: 1000 hrs : Rated current : At least 2 hrs of recovery under the	Inductance change: Within±10%		
Remarks 22.Low temperature	Temperature Duration Applied current Recovery e life test LB, LBC, LBR, LBM CB, CBC, CBL, CB LBM Series Temperature Duration	: 1000 hrs : Rated current : At least 2 hrs of recovery under the	Inductance change: Within±10% No significant abnormality in appearance.		
22.Low temperature Specified Value Test Methods and	Temperature Duration Applied current Recovery e life test LB, LBC, LBR, LBM CB, CBC, CBL, CB LBM Series Temperature	: 1000 hrs : Rated current : At least 2 hrs of recovery under the	Inductance change: Within±10%		
22.Low temperature Specified Value Test Methods and Remarks	Temperature Duration Applied current Recovery e life test LB, LBC, LBR, LBN CB, CBC, CBL, CB LBM Series Temperature Duration Recovery	: 1000 hrs : Rated current : At least 2 hrs of recovery under the	Inductance change: Within±10% No significant abnormality in appearance.		
22.Low temperature Specified Value Test Methods and	Temperature Duration Applied current Recovery e life test LB, LBC, LBR, LBN CB, CBC, CBL, CB LBM Series Temperature Duration Recovery	: 1000 hrs : Rated current : At least 2 hrs of recovery under the	Inductance change: Within±10% No significant abnormality in appearance. ne standard condition after the test, followed by the measurement within 48 hrs.		
22.Low temperature Specified Value Test Methods and Remarks	Temperature Duration Applied current Recovery e life test LB, LBC, LBR, LBN CB, CBC, CBL, CB LBM Series Temperature Duration Recovery	: 1000 hrs : Rated current : At least 2 hrs of recovery under the series MF Series : -40±2°C : 1000 hrs : At least 2 hrs of recovery under the series	Inductance change: Within±10% No significant abnormality in appearance. Standard condition after the test, followed by the measurement within 48 hrs.		
22.Low temperature Specified Value Test Methods and Remarks	Temperature Duration Applied current Recovery e life test LB, LBC, LBR, LBN CB, CBC, CBL, CB LBM Series Temperature Duration Recovery on	: 1000 hrs : Rated current : At least 2 hrs of recovery under the series MF Series : -40±2°C : 1000 hrs : At least 2 hrs of recovery under the series	Inductance change: Within±10% No significant abnormality in appearance. Standard condition after the test, followed by the measurement within 48 hrs. Standard test conditions Unless specified, Ambient temperature is 20±15°C and the Relative		
22.Low temperature Specified Value Test Methods and Remarks	Temperature Duration Applied current Recovery e life test LB, LBC, LBR, LBN CB, CBC, CBL, CB LBM Series Temperature Duration Recovery on	: 1000 hrs : Rated current : At least 2 hrs of recovery under the series MF Series MF Series : -40±2°C : 1000 hrs : At least 2 hrs of recovery under the series	Inductance change: Within±10% No significant abnormality in appearance. Standard condition after the test, followed by the measurement within 48 hrs.		
22.Low temperature Specified Value Test Methods and Remarks 23.Standard condition	Temperature Duration Applied current Recovery e life test LB, LBC, LBR, LBM CB, CBL, CB LBM Series Temperature Duration Recovery on LB, LBC, LBR, LBM	: 1000 hrs : Rated current : At least 2 hrs of recovery under the series MF Series MF Series : -40±2°C : 1000 hrs : At least 2 hrs of recovery under the series	Inductance change: Within±10% No significant abnormality in appearance. Standard condition after the test, followed by the measurement within 48 hrs. Standard test conditions Unless specified, Ambient temperature is 20±15°C and the Relative humidity is 65±20%. If there is any doubt about the test results, further measurement shall be had within the following limits: Ambient Temperature: 20±2°C		
22.Low temperature Specified Value Test Methods and Remarks 23.Standard condition	Temperature Duration Applied current Recovery e life test LB, LBC, LBR, LBM CB, CBL, CB LBM Series Temperature Duration Recovery on LB, LBC, LBR, LBM	: 1000 hrs : Rated current : At least 2 hrs of recovery under the series MF Series MF Series : -40±2°C : 1000 hrs : At least 2 hrs of recovery under the series	Inductance change: Within±10% No significant abnormality in appearance. Standard condition after the test, followed by the measurement within 48 hrs. Standard test conditions Unless specified, Ambient temperature is 20±15°C and the Relative humidity is 65±20%. If there is any doubt about the test results, further measurement shall be had within the following limits:		

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WIRE-WOUND CHIP INDUCTORS (LB SERIES), WIRE-WOUND CHIP POWER INDUCTORS (CB SERIES), WIRE-WOUND CHIP INDUCTORS FOR SIGNAL LINES (LB SERIES M TYPE)

PRECAUTIONS

Circuit Design Precautions

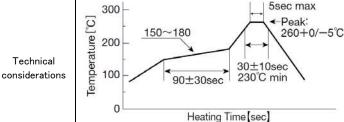
♦Operating environment

1. The products described in this specification are intended for use in general electronic equipment, (office supply equipment, telecommunications systems, measuring equipment, and household equipment). They are not intended for use in mission-critical equipment or systems requiring special quality and high reliability (traffic systems, safety equipment, aerospace systems, nuclear control systems and medical equipment including life-support systems,) where product failure might result in loss of life, injury or damage. For such uses, contact TAIYO YUDEN Sales Department in advance.

Precautions Technical considerations Technical considerations PRECAUTIONS [Recommended Land Patterns] Surface Mounting • Mounting and soldering conditions should be checked beforehand. • Applicable soldering process to those products is reflow soldering only.

3. Considerations for automatic placement				
Precautions	◆Adjustment of mounting machine 1. Excessive impact load should not be imposed on the products when mounting onto the PC boards. 2. Mounting and soldering conditions should be checked beforehand.			
Technical considerations	1. When installing products, care should be taken not to apply distortion stress as it may deform the products.			

A Soldering A Reflow soldering (LB and CB Types) 1. For reflow soldering with either leaded or lead-free solder, the profile specified in "point for controlling" is recommended. Precautions A Recommended conditions for using a soldering iron 1. Put the soldering iron on the land-pattern. Soldering iron's temperature − Below 350°C Duration−3 seconds or less. The soldering iron should not come in contact with inductor directly. A Reflow soldering (LB and CB Types) 1. Reflow profile 300 5sec max



◆Recommended conditions for using a soldering iron

1. Components can be damaged by excessive heat where soldering conditions exceed the specified range



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6. Handling	
Precautions	 ◆Handling 1. Keep the inductors away from all magnets and magnetic objects. ◆Breakaway PC boards(splitting along perforations) 1. When splitting the PC board after mounting inductors, care should be taken not to give any stresses of deflection or twisting to the board. 2. Board separation should not be done manually, but by using the appropriate devices. ◆Mechanical considerations 1. Please do not give the inductors any excessive mechanical shocks.
Technical considerations	 ◆Handling 1. There is a case that a characteristic varies with magnetic influence. ◆Breakaway PC boards(splitting along perforations) 1. Planning pattern configurations and the position of products should be carefully performed to minimize stress. ◆Mechanical considerations 1. There is a case to be damaged by a mechanical shock.

7. Storage cond	tions The state of
Precautions	 ◆Storage 1. To maintain the solderability of terminal electrodes and to keep the packing material in good condition, temperature and humidity in the storage area should be controlled. • Recommended conditions Ambient temperature: 0~40°C Humidity: Below 70% RH • The ambient temperature must be kept below 30°C. Even under ideal storage conditions, solderability of products electrodes may decrease as time passes. For this reason, product should be used within 6 months from the time of delivery. In case of storage over 6 months, solderability shall be checked before actual usage.
Technical considerations	◆Storage 1. Under a high temperature and humidity environment, problems such as reduced solderability caused by oxidation of terminal electrodes and deterioration of taping/packaging materials may take place.